

**PRELIMINARY DATA SHEET**

# SKY65124: 1930–1990 MHz High Linearity 2 W Power Amplifier

## Applications

- WCDMA/PCS/DCS/UTMS/TD-SCDMA
- Repeaters
- ISM band transmitter
- WCS fixed wireless

## Features

- High linearity: OIP3 > 45 dBm
- $P_{1\text{ dB}} > 33\text{ dBm}$
- ACLR = -45 dBc for  $P_{\text{OUT}} > 25\text{ dBm}$
- ACLR = -55 dBc for  $P_{\text{OUT}} > 21\text{ dBm}$
- High efficiency: PAE 35%
- High gain: 24 dB
- Single DC supply: 5 V
- Internal RF match with DC block
- Active bias circuit
- MCM (20-pin, 6 x 6 mm) lead (Pb)-free package (MSL3 @ 260 °C per JEDEC J-STD-020)

## Description

The SKY65124 is a fully matched 20-pin, lead-free, surface mount, Multichip Module (MCM) Power Amplifier (PA) designed for WCDMA/PCS/DCS/UTMS/TD-SCDMA radio, repeaters, transmitters, mobile radios and WCS fixed wireless applications operating in the 1930–1990 MHz bandwidth.

All active circuitry in the module is contained in a single Gallium Arsenide (GaAs) Microwave Monolithic Integrated Circuit (MMIC).

The device is manufactured with Skyworks Aluminum (Al) GaAs Heterojunction Bipolar Transistor (HBT) process, which allows for single supply operation while maintaining high efficiency and good linearity.

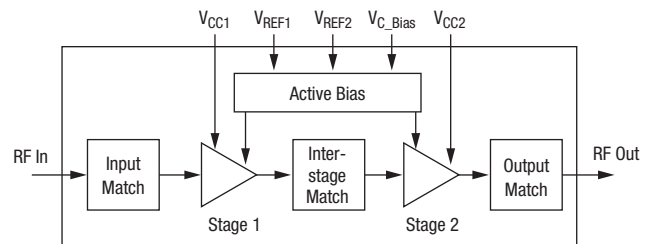
The module can operate over the temperature range of -40 °C to +85 °C. A populated evaluation board is available upon request.

**NEW** Skyworks offers lead (Pb)-free, RoHS (Restriction of Hazardous Substances)-compliant packaging.

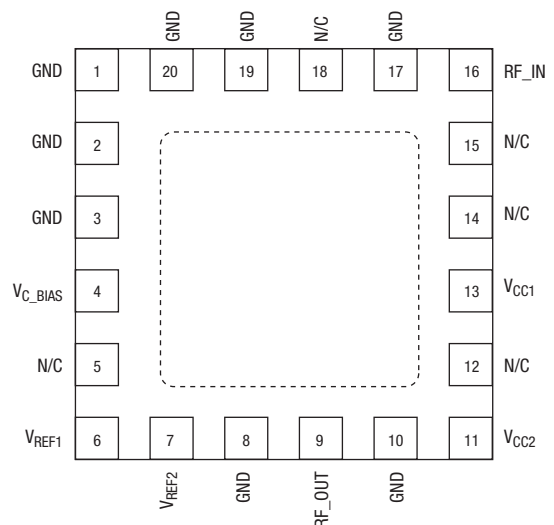


**Preliminary Data Sheet:** Based on engineering results. Sampling quantities available. Pin out and package have been determined.

## Block Diagram



## Package Diagram



### Electrical Specifications

**V<sub>CC1</sub>, V<sub>CC2</sub>, V<sub>REF1</sub>, V<sub>REF2</sub>, V<sub>C\_BIAS</sub> = 5 V, Test Frequency = 1960 MHz, T<sub>C</sub> = 25 °C, Z<sub>0</sub> = 50 Ω, unless otherwise specified**

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Frequency	F		1930		1990	MHz
Small signal gain	S <sub>21</sub>	Small signal		24		dB
Input return loss	S <sub>11</sub>	Small signal		29		dB
Output return loss	S <sub>22</sub>	Small signal		15		dB
Output power @ P <sub>1</sub> dB	P <sub>1</sub> dB	CW		33		dBm
Output 3rd order intercept	OIP3	P <sub>OUT</sub> /tone = 25 dBm, tone spacing= 5 MHz		45		dBm
Noise figure	NF	CW		6.3		dB
P <sub>OUT</sub> @ ACLR = -45 dBc	P <sub>OUT_ACLR1</sub>	WCDMA test tone #1: 64 DPCH, ΔF = 5 MHz	25			dBm
P <sub>OUT</sub> @ ACLR = -55 dBc	P <sub>OUT_ACLR2</sub>	WCDMA test tone #1: 64 DPCH, ΔF = 10 MHz	21			dBm
Power-added efficiency	PAE	CW, P <sub>OUT</sub> @ P <sub>1</sub> dB		39		%
Quiescent current	I <sub>CCQ</sub>	No RF signal		500		mA
Thermal resistance	Θ <sub>JC</sub>	Junction to case		22		°C/W

### Absolute Maximum Ratings

Characteristic	Value
RF input power (P <sub>OUT</sub> )	5 dBm
Supply voltage (V <sub>CC</sub> , V <sub>REF</sub> , V <sub>C_BIAS</sub> )	6 V
Total supply current (I <sub>CC</sub> + I <sub>BIAS</sub> + I <sub>REF</sub> )	1100 mA
Operating case temperature (T <sub>C</sub> )	-40 °C to +85 °C
Storage temperature (T <sub>ST</sub> )	-55 °C to +125 °C
Junction temperature (T <sub>J</sub> )	150 °C

Performance is guaranteed only under the conditions listed in the specifications table and is not guaranteed under the full range(s) described by the Absolute Maximum specifications. Exceeding any of the absolute maximum/minimum specifications may result in permanent damage to the device and will void the warranty. Each absolute maximum rating listed is an individual parameter. Biasing and driving the amplifier with more than one absolute maximum rating listed may result in permanent damage to the device. Exposure to maximum rating conditions for extended periods may reduce device reliability.

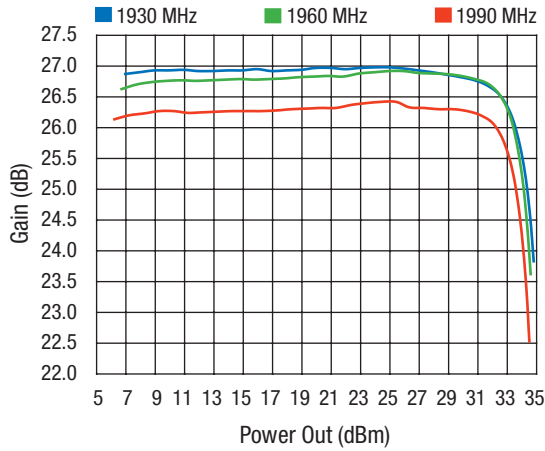
**CAUTION:** *Although this device is designed to be as robust as possible, Electrostatic Discharge (ESD) can damage this device. This device must be protected at all times from ESD. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD precautions should be employed at all times.*

### Recommended Operating Conditions

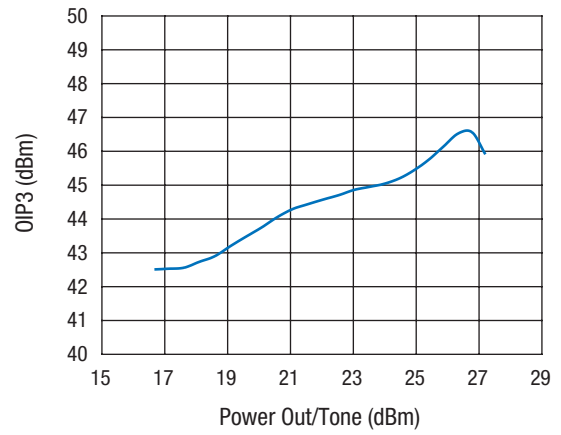
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Operating frequency	F <sub>0</sub>		1930		1990	MHz
RF input power (small signal)	P <sub>IN</sub>			-10		dBm
Supply voltages (Note 1)	V <sub>CC</sub> , V <sub>C_BIAS</sub> , V <sub>REF</sub>			5		V
Operating case temperature	T <sub>C</sub>		-40	25	85	°C

### Typical Performance Data

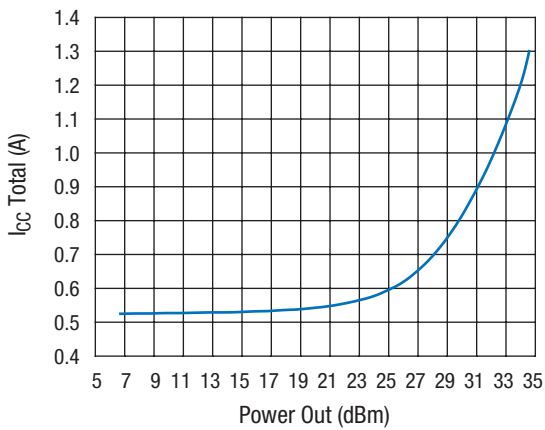
$V_{CC1}$ ,  $V_{CC2}$ ,  $V_{REF1}$ ,  $V_{REF2}$ ,  $V_{C\_BIAS}$  = 5 V, Test Frequency = 1960 MHz,  $T_c$  = 25 °C,  $Z_0$  = 50  $\Omega$ , unless otherwise specified



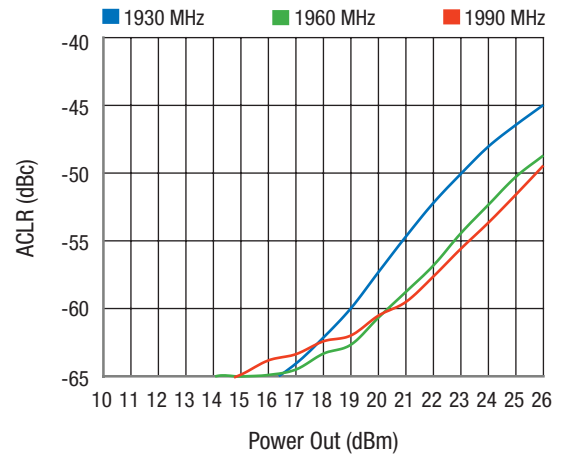
Gain vs. Power Out Across Frequency



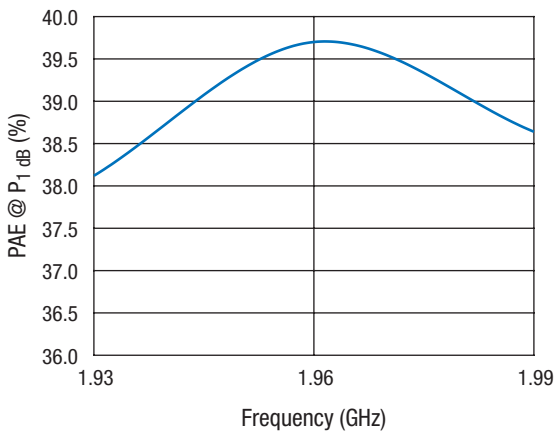
OIP3 vs. Power Out/Tone Across Frequency  
 $\Delta F$  = 5 MHz



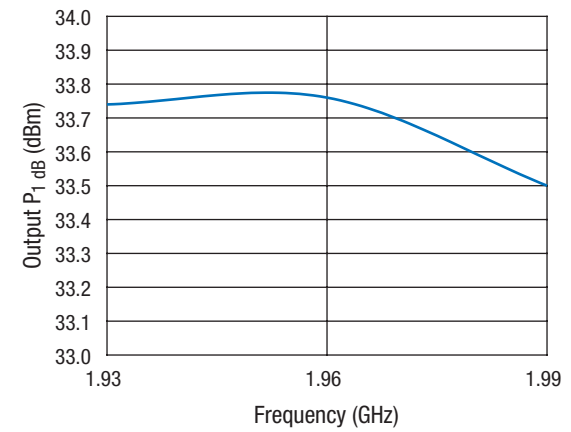
Total Collector Current vs. Power Out



ACLR vs. Power Out Across Frequency  
WCDMA Test Tone #1; 64 DPCH,  $\Delta F$  = 5 MHz



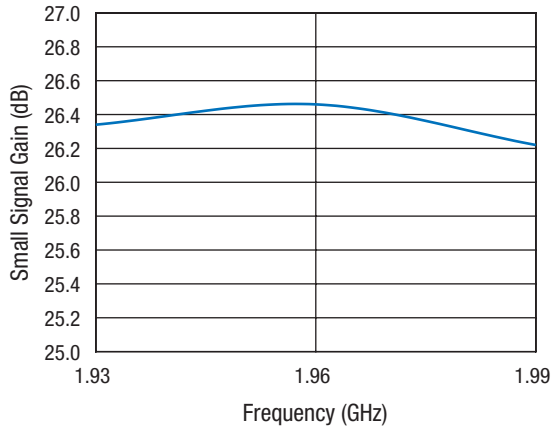
PAE @  $P_1$  dB vs. Frequency



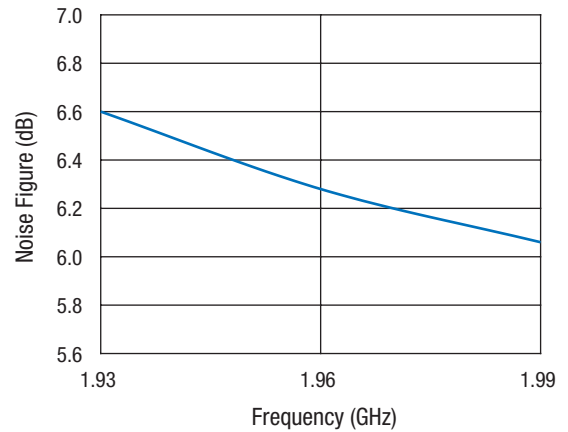
Output  $P_1$  dB vs. Frequency

### Typical Performance Data

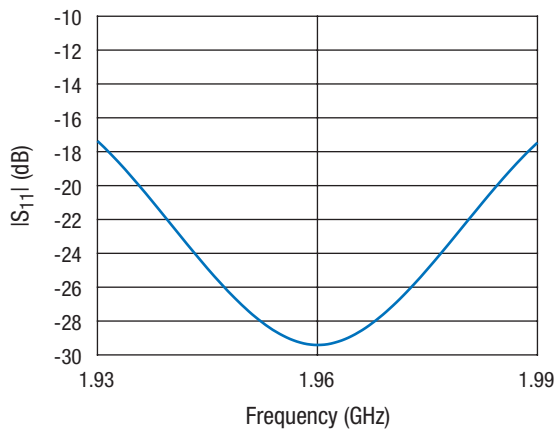
$V_{CC1}$ ,  $V_{CC2}$ ,  $V_{REF1}$ ,  $V_{REF2}$ ,  $V_{C\_BIAS}$  = 5 V, Test Frequency = 1960 MHz,  $T_c$  = 25 °C,  $Z_0$  = 50  $\Omega$ , unless otherwise specified



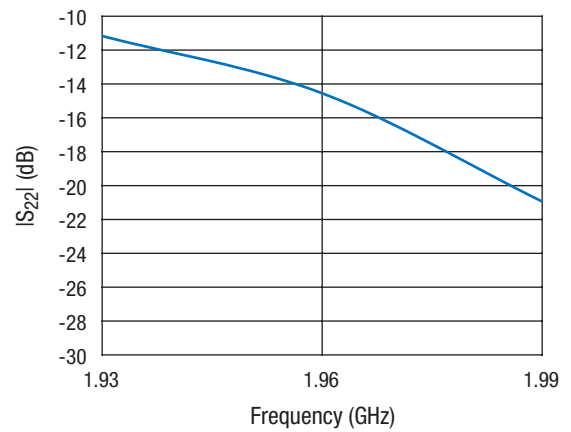
**Small Signal Gain vs. Frequency**



**Noise Figure vs. Frequency**



**$|S_{11}|$  vs. Frequency**



**$|S_{22}|$  vs. Frequency**

## Theory of Operation

The SKY65124 is comprised of two amplifier stages. The matching circuits for the input stage, inter-stage, and output stage are contained within the device. An on-chip active bias circuit is included within the device for both input and output stages providing for excellent gain tracking over temperature and voltage variations.

The SKY65124 is internally matched for optimum linearity and efficiency. The input and output stages are independently supplied using the  $V_{CC1}$  and  $V_{CC2}$  supply lines, pins 13 and 11, respectively. The bias reference voltages for stages 1 and 2 are supplied using common lines  $V_{REF1}$  and  $V_{REF2}$  (pins 6 and 7) line. The DC control voltage that sets the bias to stages 1 and 2 is supplied via  $V_{C\_BIAS}$ , pin 4.

## Application Circuit Notes

**Center Ground.** It is extremely important that the device paddle be sufficiently grounded for both thermal and stability reasons. Multiple small vias are acceptable and will work well under the device if solder migration is an issue.

**Ground (Pins 1, 2, 3, 8, 10, 17, 19, 20).** Attach all ground pins to the RF ground plane with the largest diameter and lowest inductance via that the layout will allow. Multiple small vias are also acceptable and will work well under the device if solder migration is an issue.

**No Connect (Pins 5, 12, 14, 15, 18).** The pins are open and may or may not be connected to ground.

**$V_{C\_BIAS}$  (Pin 4).**  $V_{C\_BIAS}$  is the bias supply voltage for stages 1 and 2. Typically set to 5 V.

**$V_{REF1}$  (Pin 6).** Bias reference voltage for amplifier stage 1.  $V_{REF1}$  should be operated over the same voltage range as  $V_{CC}$ , with a nominal voltage of 5 V.

**$V_{REF2}$  (Pin 7).** Bias reference voltage for amplifier stage 2.  $V_{REF2}$  should be operated over the same voltage range as  $V_{CC}$ , with a nominal voltage of 5 V.

**RF\_OUT (Pin 9).** Amplifier RF Output Pin.  $Z_0 = 50 \Omega$ . The module includes an onboard internal DC blocking capacitor. All impedance matching is provided internal to the module.

**$V_{CC2}$  (Pin 11).** Supply voltage for the output (final) stage collector bias (typically 5 V). Bypassing of  $V_{CC2}$  is accomplished with C10, C11 and C12 and should be placed in the approximate location shown on the evaluation board, but placement is not critical.

**$V_{CC1}$  (Pin 13).** Supply voltage for the first stage collector bias (typically 5 V). Bypassing of  $V_{CC1}$  is accomplished with C6, C7 and C8 and should be placed in the approximate location shown on the evaluation board, but placement is not critical.

**RF\_IN (Pin 16).** Amplifier RF Input Pin.  $Z_0 = 50 \Omega$ . The module includes an onboard internal DC blocking capacitor. All impedance matching is provided internal to the module.

### Package and Handling Information

Since the device package is sensitive to moisture absorption, it is baked and vacuum packed before shipping. Instructions on the shipping container label regarding exposure to moisture after the container seal is broken must be followed. Otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

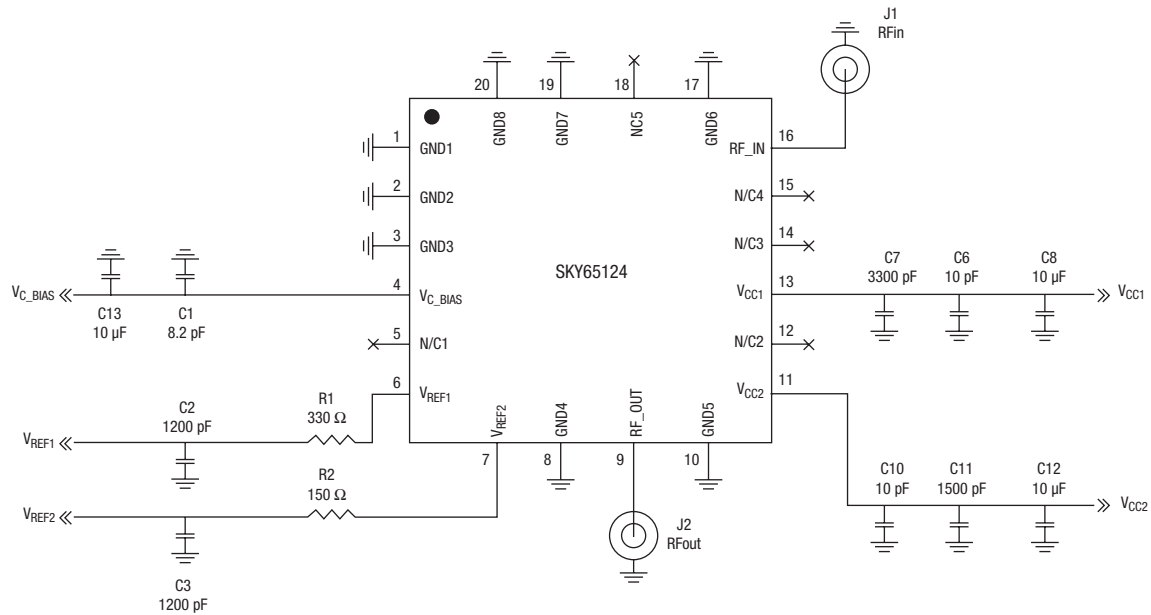
Please refer to Skyworks' *Solder Reflow* application note, available at [www.skyworksinc.com](http://www.skyworksinc.com), for instructions on mounting the SKY65124 to a printed circuit board.

Production quantities of this product are shipped in a standard tape and reel format. For packaging details, refer to the Skyworks *Tape and Reel* application note, document number 101568.

### Electrostatic Discharge (ESD) Sensitivity

The SKY65124 is a static-sensitive electronic device. Do not operate or store near strong electrostatic fields. Take proper ESD precautions.

### Application Circuit



## Pin Assignments

Pin	Pin Name	Description
1	GND	Low inductance ground connection
2	GND	Low inductance ground connection
3	GND	Low inductance ground connection
4	V <sub>C_BIAS</sub>	Bias voltage
5	N/C	No connect
6	V <sub>REF1</sub>	Bias reference voltage 1
7	V <sub>REF2</sub>	Bias reference voltage 2
8	GND	Low inductance ground connection
9	RF_OUT	RF output
10	GND	Low inductance ground connection
11	V <sub>CC2</sub>	Stage 2 collector voltage
12	N/C	No connect
13	V <sub>CC1</sub>	Stage 1 collector voltage
14	N/C	No connect
15	N/C	No connect
16	RF_IN	RF input
17	GND	Low inductance ground connection
18	N/C	No connect
19	GND	Low inductance ground connection
20	GND	Low inductance ground connection

Center attachment pad must have a low inductance and low thermal resistance connection to the customer's printed circuit board ground plane.

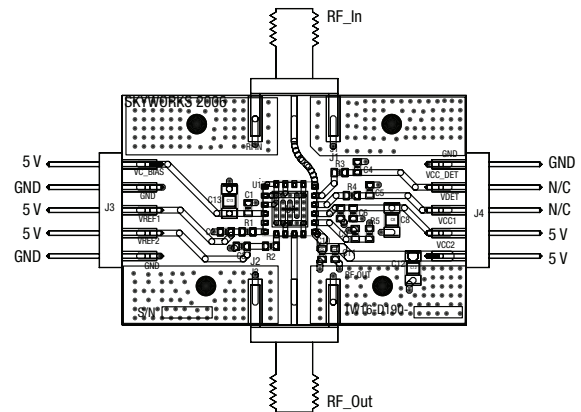
## Evaluation Board Description

The Skyworks SKY65124 Evaluation Board is used to test the performance of the SKY65124 power amplifier module. The following design considerations are general in nature and must be followed regardless of final use or configuration.

1. Paths to ground should be made as short as possible.
2. The ground pad of the SKY65124 power amplifier module has special electrical and thermal grounding requirements. This pad is the main thermal conduit for heat dissipation. Since the circuit board acts as the heat sink, it must shunt as much heat as possible from the amplifiers. As such, design the connection to the ground pad to dissipate the maximum wattage produced to the circuit. Multiple vias to the grounding layer are required.

**NOTE:** Junction temperature ( $T_j$ ) of the device increases with a poor connection to the slug and ground. This reduces the lifetime of the device.

## Evaluation Board



## Evaluation Board Test Procedure

- Step 1. Connect RF test equipment to amplifier input/output SMA connectors.
- Step 2. Connect DC ground.
- Step 3. Connect all V<sub>CC</sub>, V<sub>REG</sub> and V<sub>C\_BIAS</sub> lines to 5 V supply. Verify the I<sub>CCQ</sub> current is approximately 550 mA.
- Step 4. Apply RF signal data -10 dBm level and observe that the output level is approximately 14 dBm or the gain of the device is approximately 24 dB.

**NOTE:** It is important that the V<sub>CC1</sub> and V<sub>CC2</sub> voltage source be adjusted such that 5 V is measured at the board. The high collector currents will drop the collector voltage significantly if long leads are used. Adjust the bias voltage to compensate.

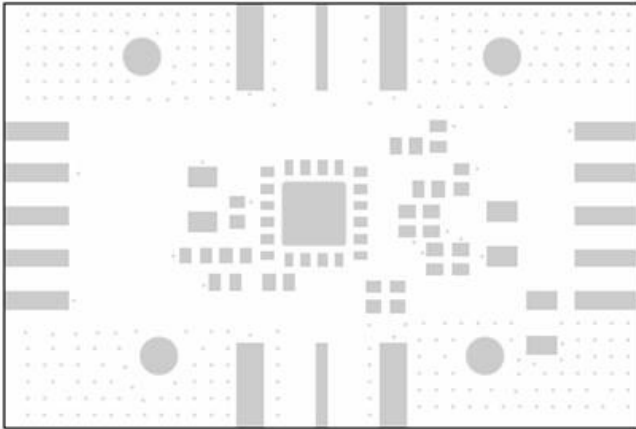
## Recommended Solder Reflow Profiles

Refer to the "[Recommended Solder Reflow Profile](#)" Application Note.

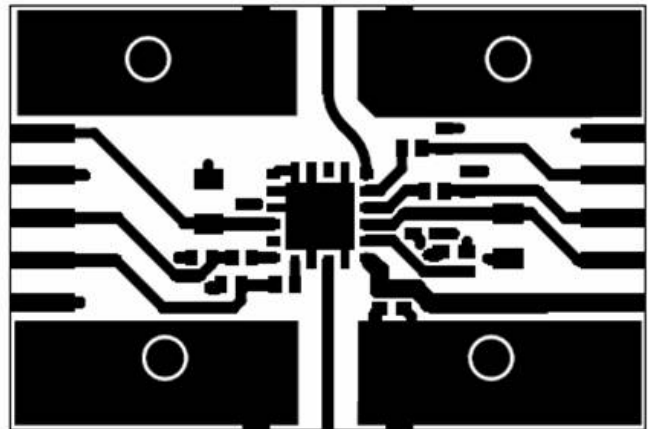
## Tape and Reel Information

Refer to the "[Discrete Devices and IC Switch/Attenuators Tape and Reel Package Orientation](#)" Application Note.

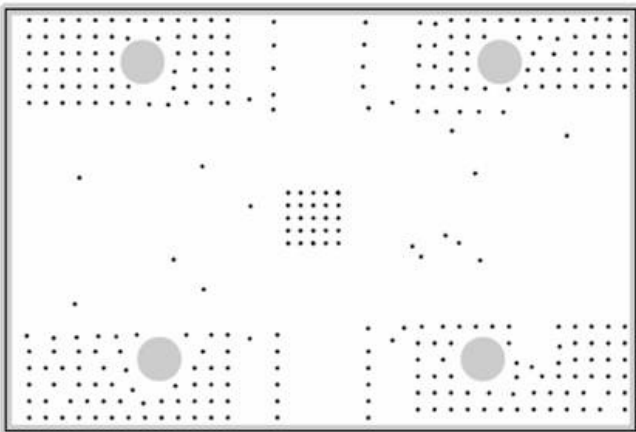
### Evaluation Board Layer Detail



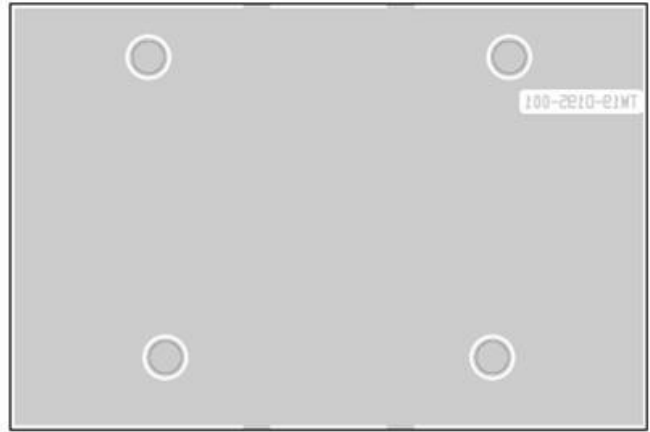
**Layer 1: Solder Mask**



**Layer 1: Top Metal**



**Layer 2 and 3: Ground**



**Layer 4: Solid Ground Plane**



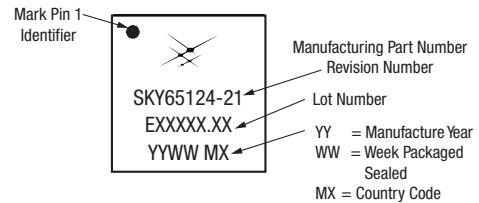
### Bill of Material for Evaluation Board

Part	ID	Qty.	Size	Value	Units	Product Number	Manufacturer	Manufacturer's Part Number	Characteristics
1	C1	1	0603	8.2	pF	5404R23-046	Murata	GRM1885C1H8R2CZ01D	COG, 50 V, ± 0.25 pF
2	C2	1	0603	1200	pF	SK204-000-002	Murata	GRM1887U1H122J	U2J, 50 V, ± 5%
3	C3	1	0603	1200	pF	SK204-000-002	Murata	GRM1887U1H122J	U2J, 50 V, ± 5%
4	C6	1	0603	10	pF	5404R23-047	Murata	GRM1885C1H100RD51D	COG, 50 V, ± 0.25 pF
5	C7	1	0603	3300	pF	5404R28-015	Murata	GRM188R71H332KD01J	X7R, 50 V, ± 10%
6	C8	1	1206	10	µF	5404R91-005	TDK	C3216X5R0J106KT	X5R, 6 V, ± 10%
7	C10	1	0603	10	pF	5404R23-047	Murata	GRM1885C1H100RD51D	COG, 50 V, ± 0.25 pF
8	C11	1	0603	1500	pF	5404R24-015	AVX	06031C152MATMA	X7R, 100 V, ± 20%
9	C12	1	1206	10	µF	5404R91-005	TDK	C3216X5R0J106KT	X5R, 6 V, ± 10%
10	C13	1	1206	10	µF	5404R91-005	TDK	C3216X5R0J106KT	X5R, 6 V, ± 10%
11	R1	1	0603	330	Ω	5424R20-037	ROHM	MCR03EZHUJ330	50 V, 0.063W, ± 5%
12	R2	1	0603	150	Ω	5424R19-114	ROHM	MCR03EZHUJ150	50 V, 0.063W, ± 1%

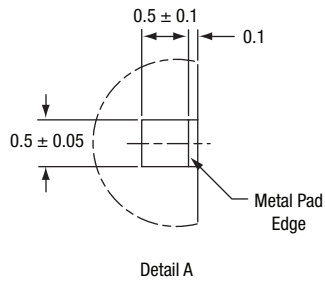
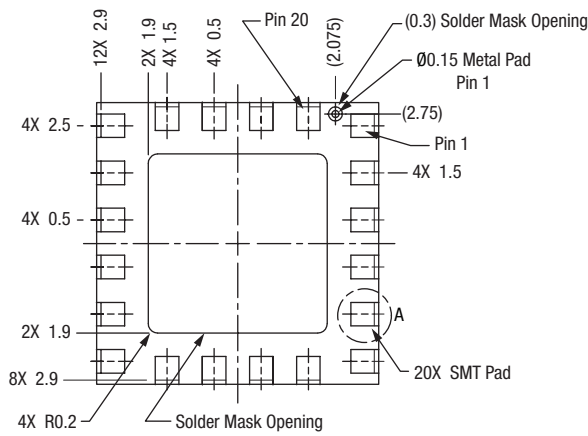
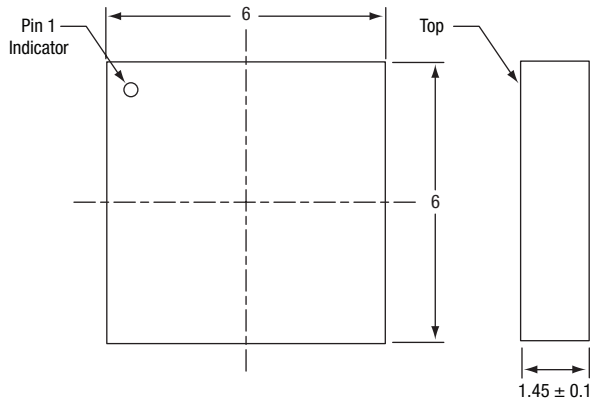
### Evaluation Board Stack-Up

Cross Section	Name	Thickness (mils)	Material	ε <sub>r</sub>
	L1	1.4	Cu	-
	Lam1	12	Rogers 4003-12	3.38
	L2_GND	1.4	Cu, 1 oz.	-
	Lam2	4	FR4-4	4.35
	L3_GND	1.4	Cu, 1 oz.	-
	Lam3	12	FR4-12	4.35
	L4	1.4	Cu, 1 oz.	-

### Branding Specifications

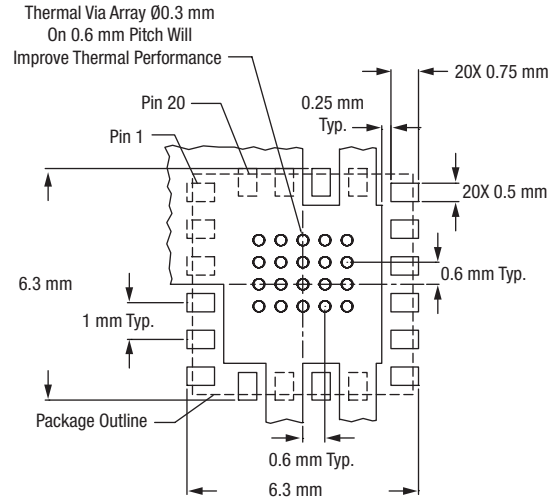


### Package Dimensions

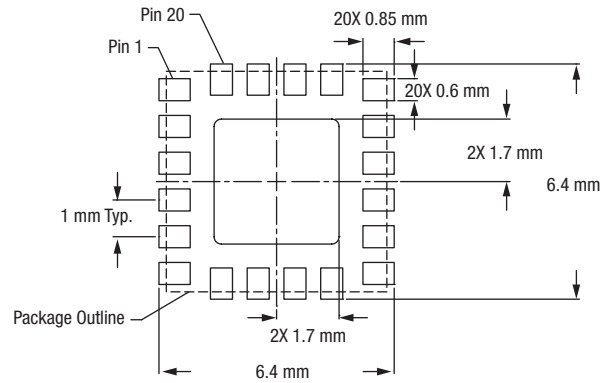


All dimensions are in millimeters  
Dimensioning and tolerancing according  
to ASME Y14.5M-1994

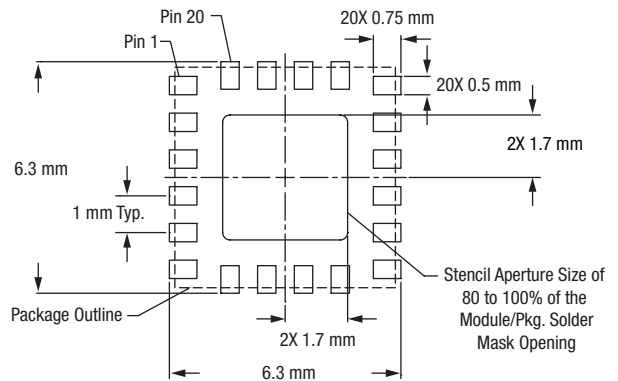
### Recommended Footprint



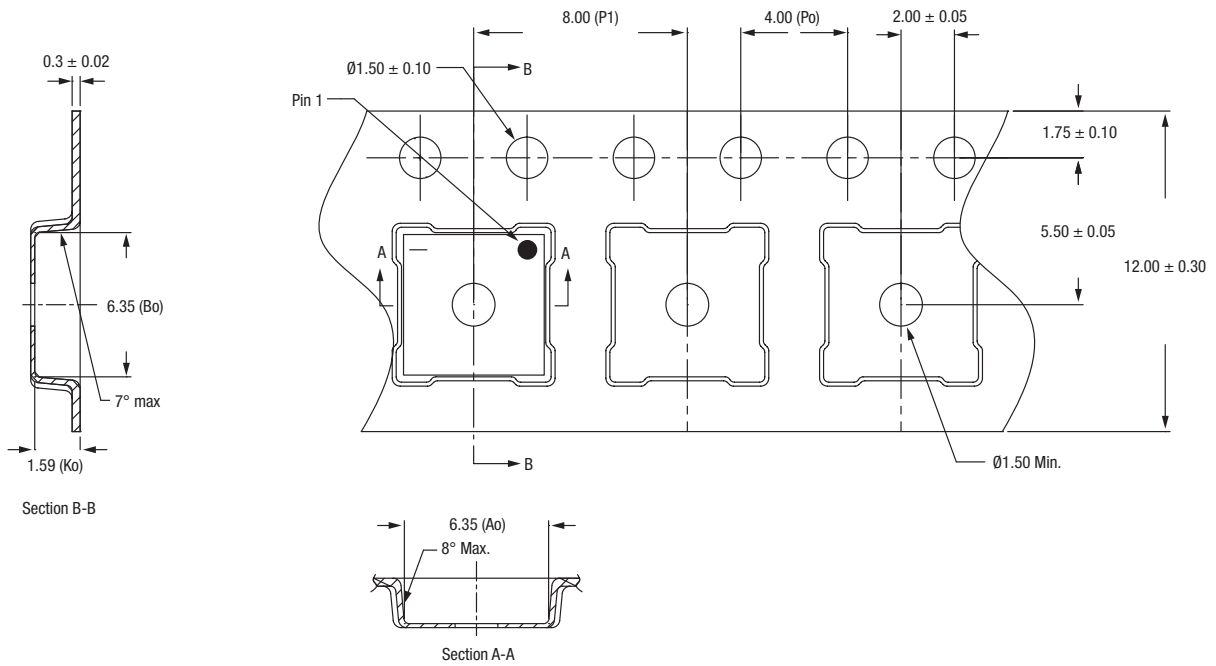
### Solder Mask



### Stencil Pattern



## Tape and Reel Dimensions



1. Carrier tape: black conductive polystyrene
2. Cover tape material: transparent conductive PSA
3. Cover tape size: 9.3 mm width
4. All dimensions are in millimeters

## Ordering Information

Model Name	Manufacturing Part Number	Evaluation Kit Part Number
SKY65124: 1930–1990 MHz High Linearity 2 W Power Amplifier	SKY65124-21 (Pb-free package)	TW16-D193-001

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